IPC ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	ials and Mfg Information				
upplier l	Information														
Company name* Company				npany unique ID			Unique ID Authority				Respon	Response Date*			
nsemi											2025-08	2025-08-02			
Contact Na	me	Title - Contact			I	Phone - Contact*				Email -	Email - Contact*				
?roduct-En	nv-Stewards		Product Enviro Compliance]	NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			F	Phone - Representative*				Email -	Email - Representative*				
roduct-En	nv-Stewards		Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Item	Number	mber Mfr Item Name			Effective Date	Version	on Manufacturing Site			Weight*	UOM	Unit Type	
	2SC6099-TL-E BIP		BIP NPN 2A 100V			2025-08-02		C	CNG		281.12	mg	Each		
	turing Proccess Inform		erminal Base	Alloy	STD-020 MS	I. Poting	Pank Proce	es Rody Ta	mparatur	Max Time at Pea	k Tampara	tura Numb	per of Reflow Cyo	elec	
		CU Alloy 1		31D-020 M3	L Katilig	Peak Process Body Temperate 260 C			30			bei of Kerlow Cyt	cies		
-	ontains Di		Alloy	1			200		<u> </u>	30	seco	ius 3			
omments	ximum time at peak tempera	tuno dunina col	Idoring is 10.3	20 seconds											
	ximum time at peak tempera iformation regarding materia														

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.44	mg	Supplier	Silicon (Si)	7440-21-3		0.44	mg
Die Attach Solder	0.22	mg	Supplier	Silver (Ag)	7440-22-4		0.0055	mg
			A	Lead (Pb)	7439-92-1	7a	0.2035	mg
			Supplier	Tin (Sn)	7440-31-5		0.011	mg
Lead Frame	146.44	mg	Supplier	Silver (Ag)	7440-22-4		0.3807	mg
			Supplier	Tin (Sn)	7440-31-5		0.205	mg
			Supplier	Copper (Cu)	7440-50-8		145.8542	mg
Mold Compound-Black	130.26	mg		Brominated epoxy resin	proprietary data		1.8236	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.8617	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1723	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3026	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		97.695	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		22.1442	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2605	mg
Plating	3.34	mg	В	Bismuth (Bi)	7440-69-9		0.02	mg
-			Supplier	Tin (Sn)	7440-31-5		3.32	mg
Wire Bond - Au	0.42	mg	Supplier	Gold (Au)	7440-57-5		0.42	mg